

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SOICHIRO UMEDA	03/09/2021
ATSUSHI KYUTOKU	03/09/2021
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SHINDENGEN ELECTRIC MANUFACTURING CO., LTD.
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<b>City:</b>	TOKYO
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<b>Postal Code:</b>	100-0004
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	35508564
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<b>ATTORNEY DOCKET NUMBER:</b>	4592-140DES
<b>NAME OF SUBMITTER:</b>	YUKIKO YOSHINAGA
<b>SIGNATURE:</b>	/Yukiko Yoshinaga/
<b>DATE SIGNED:</b>	03/22/2021
<b>Total Attachments: 1</b>	
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**ASSIGNMENT**

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

1) Soichiro UMEDA

2) Atsushi KYUTOKU

who has made a certain new and useful invention, hereby sells, assigns and transfers unto SHINDENGEN ELECTRIC MANUFACTURING CO., LTD. having a place of business at 2-1, Otemachi 2-chome, Chiyoda-ku, Tokyo 100-0004 Japan, its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled:

**Power module device containing semiconductor elements**

(a) for which an application for United States Letters Patent was filed on March 29, 2019, and identified by United States Patent Application No. 35/508,564; or

(b) for which an application for United States Letters Patent was executed on \_\_\_\_\_,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Soichiro Umeda  
Name: Soichiro UMEDA

March 9, 2021  
Date

2) Atsushi Kyutoku  
Name: Atsushi KYUTOKU

March 9, 2021  
Date